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Semiconductor devices – Micro-electromechanical devices – Part 42: Measurement methods of electro-mechanical conversion characteristics of piezoelectric MEMS cantilever

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Part 42: Measurement methods of electro-mechanical conversion characteristics of piezoelectric MEMS cantilever

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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 42: Measurement methods of electro-mechanical conversion characteristics of piezoelectric MEMS cantilever

1 Scope

This part of IEC 62047 specifies measuring methods of electro-mechanical conversion characteristics of piezoelectric thin film on microcantilever, which is typical structure of actual micro sensors and micro actuators. In order to obtain actual and precise piezoelectric coefficient of the piezoelectric thin films with microdevice structures, and this document reports the schema to determine the characteristic parameters for consumer, industry or any other applications of piezoelectric devices. This document applies to piezoelectric thin films on microcantilever fabricated by MEMS process.

2 Normative references

There are no normative references in this document.